Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An anisotropic conductive adhesive ~~material~~film, for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying the electronic component, the anisotropic conductive adhesive ~~material~~ film comprising at least one curable resin and silica particles, wherein:

the silica particles have a specific surface area S (m^2/g) satisfying Equation (1) below;

$$~~11 < S \leq 17~~ 11 \leq S \leq 17 \quad (1);$$

the silica particles have a mean particle size D_1 (μm) and maximum particle size D_2 (μm) satisfying Equations (2) and (3) below, respectively,

$$D_1 \leq 5 \quad (2);$$

$$D_2 \leq 0.5\ (h_1 + h_2) \quad (3);$$

wherein h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit board,

the content of the silica particles is 35 to 60 vol%, and

the mean particle size D_1 of the silica particles further satisfies the Equation (4) below,

$$0.1(h_1 + h_2) \geq D_1 \quad (4);$$

wherein the anisotropic conductive adhesive ~~material~~ film further comprises conductive particles having a mean particle size of 0.5 to 8.0 μm; ~~and~~

wherein the anisotropic conductive adhesive ~~material~~ film has a coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less; and

wherein the anisotropic conductive adhesive film undergoes indentation of at least 10 μm at a 1 kgf indentation strength, and undergoes indentation of at least 15 μm at an indentation strength of 2 kgf, during thermocompression bonding for 20 seconds at 180°C.

2-5. (Canceled)

6. (Previously Presented) The adhesive material according to Claim 1, wherein the electronic component is a semiconductor element.

7. (Canceled)